Electronic Version
Stylesheet Version v1.1.1

Claims

[c1] 1. A method of fabricating an active matrix organic light emitting diode, comprising:
providing a substrate having a display area and a non-display area thereon, wherein the display area comprises a plurality of pixel structures thereon;
forming a plurality of transparent conductive lines electrically connected to the pixel structures and extending from the display area towards the non-display area;
disposing a cap over the substrate to cover the display area;
applying a photosensitive glue at a perimeter of the display area between the cap and the substrate, so that the cap is adhered to the substrate thereby;
performing a radiation step to cure the photosensitive glue; and
forming a driving chip in the non-display area of the substrate, wherein the driving chip is electrically connected to the pixel structures via the transparent conductive lines.

[c2] 2. The method according to Claim 1, wherein the transparent conductive line is made of indium tin oxide or in-

dium zinc oxide.

[c3] 3. The method according to Claim 1, wherein the transparent conductive line has a length of about 2mm to about 4mm.

[c4] 4. The method according to Claim 1, wherein the photosensitive glue includes an ultra-violet glue.

[c5] 5. The method according to Claim 4, wherein the radiation step further comprises an ultra-violet radiation step.

[c6] 6. The method according to Claim 5, wherein the cap includes metal cap or a glass cap.